

Title (en)
Heat pump type hot water supply system

Title (de)
Heizwasserversorgungsanlage mit Wärmepumpe

Title (fr)
Installation à eau chaude avec pompe à chaleur

Publication
EP 1298395 A3 20040114 (EN)

Application
EP 02021700 A 20020927

Priority
JP 2001302126 A 20010928

Abstract (en)
[origin: EP1298395A2] A heat pump type hot water supply system includes a hot water storage tank (3), and a circulation line (12) connecting a water outlet (10) at the lower part of the storage tank (3) and a hot water inlet (11) at the upper part thereof. The circulation line (12) is provided partway therealong with a heat exchange line (14) to be heated by a heat pump heat source. The system is configured to return hot water heated up in the heat exchange line (14) to the hot water storage tank (3) through the hot water inlet (11). When the heated water temperature of the heat exchange line (14) is equal to or below a set point, the return of the water to the hot water storage tank (3) through the hot water inlet (11) is hindered, and when the heated temperature of the heat exchange line (14) is above the set point, the outgoing water from the heat exchange line (14) is returned to the hot water storage tank (3) through the hot water inlet (11). <IMAGE>

IPC 1-7
F24D 17/02; **F24D 19/10**; **F24H 4/04**; **F24H 9/20**

IPC 8 full level
F24H 1/00 (2006.01); **F24D 17/02** (2006.01); **F24D 19/10** (2006.01)

CPC (source: EP US)
F24D 17/02 (2013.01 - EP); **F24D 19/1054** (2013.01 - EP US); **F24H 4/04** (2013.01 - EP); **F24H 9/2021** (2013.01 - EP); **F24H 15/136** (2022.01 - EP US); **F24H 15/164** (2022.01 - EP US); **F24H 15/227** (2022.01 - EP US); **F24H 15/242** (2022.01 - EP US); **F24H 15/385** (2022.01 - EP US); **F24H 15/414** (2022.01 - EP US); **F24D 2220/042** (2013.01 - EP); **F24D 2240/26** (2013.01 - EP)

Citation (search report)

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- [XY] EP 0686816 A1 19951213 - CTC FERRO FIL A S [NO]
- [X] JP 2001263800 A 20010926 - DAIKIN IND LTD
- [Y] PATENT ABSTRACTS OF JAPAN vol. 018, no. 411 (M - 1648) 2 August 1994 (1994-08-02)
- [A] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 26 1 July 2002 (2002-07-01)
- [A] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 01 31 January 1997 (1997-01-31)
- [A] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 09 31 July 1998 (1998-07-31)

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